

ABSTRACT OF THE DISCLOSURE

A semiconductor light-emitting device includes a lead frame having a main surface, a LED chip, an epoxy resin provided to completely cover the LED chip, and a resin portion provided to surround the LED chip. The epoxy resin includes a top surface. The resin portion includes a top surface at a position where a distance from the main surface is greater than a distance from the main surface to the top surface, and an inner wall provided on the side where the LED chip is located and extending in a direction away from the main surface to reach the top surface. Thus, the semiconductor light-emitting device excellent in heat radiation and permitting appropriate control of directivity of the light, a manufacturing method thereof, and an electronic image pickup device are provided.